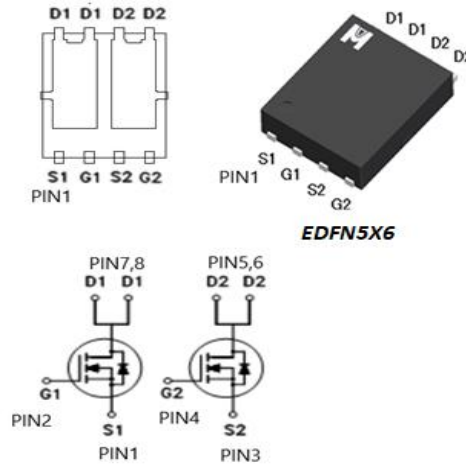


Dual N-Channel Logic Level Enhancement Mode Field Effect Transistor

•Product Summary:

	N-CH
BVDSS	60V
$R_{\text{DS(on)}}(\text{MAX.})@V_{\text{GS}}=10\text{V}$	120mΩ
$R_{\text{DS(on)}}(\text{MAX.})@V_{\text{GS}}=4.5\text{V}$	180mΩ
$I_{\text{D}}@T_{\text{C}}=25^{\circ}\text{C}$	11A

• Pin Description:



Dual N Channel MOSFET  
UIS, Rg 100% Tested  
Pb-Free Lead Plating & Halogen Free



•ABSOLUTE MAXIMUM RATINGS ( $T_{\text{C}} = 25^{\circ}\text{C}$  Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		$V_{\text{GS}}$	$\pm 20$	V
Continuous Drain Current	$T_{\text{C}} = 25^{\circ}\text{C}$	$I_{\text{D}}$	11	A
	$T_{\text{C}} = 100^{\circ}\text{C}$		7.3	
Pulsed Drain Current <sup>1</sup>		$I_{\text{DM}}$	44	
Avalanche Current		$I_{\text{AS}}$	5	mJ
Avalanche Energy	$L = 0.1\text{mH}$	EAS	1.25	
Repetitive Avalanche Energy <sup>2</sup>	$L = 0.05\text{mH}$	EAR	0.63	
Power Dissipation	$T_{\text{C}} = 25^{\circ}\text{C}$	$P_{\text{D}}$	25	W
	$T_{\text{C}} = 100^{\circ}\text{C}$		10	
Operating Junction & Storage Temperature Range		$T_{\text{j}}, T_{\text{stg}}$	-55 to 150	$^{\circ}\text{C}$

•THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta\text{JC}}$		5	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient <sup>3</sup>	$R_{\theta\text{JA}}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle < 1%

<sup>3</sup>62.5 $^{\circ}\text{C} / \text{W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



▪ ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1	1.7	2.5	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V			1	uA
		V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C			25	
On-State Drain Current <sup>1</sup>	I <sub>D(ON)</sub>	V <sub>DS</sub> = 5V, V <sub>GS</sub> = 10V	8			A
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A		100	120	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4A		150	180	
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5A		8		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 30V, f = 1MHz		112		pF
Output Capacitance	C <sub>oss</sub>			57		
Reverse Transfer Capacitance	C <sub>rss</sub>			13		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 15mV, V <sub>DS</sub> = 0V, f = 1MHz		3.5		Ω
Total Gate Charge <sup>1,2</sup>	Q <sub>g</sub> (V <sub>GS</sub> =10V)	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 8A		3.2		nC
	Q <sub>g</sub> (V <sub>GS</sub> =4.5V)			2.1		
Gate-Source Charge <sup>1,2</sup>	Q <sub>gs</sub>			0.5		
Gate-Drain Charge <sup>1,2</sup>	Q <sub>gd</sub>			2.1		
Turn-On Delay Time <sup>1,2</sup>	t <sub>d(on)</sub>		V <sub>DS</sub> = 30V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 1A, R <sub>g</sub> = 6Ω		3.2	
Rise Time <sup>1,2</sup>	t <sub>r</sub>			3		
Turn-Off Delay Time <sup>1,2</sup>	t <sub>d(off)</sub>			7.2		
Fall Time <sup>1,2</sup>	t <sub>f</sub>			18.4		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>C</sub> = 25 °C)</b>						
Continuous Current	I <sub>S</sub>				11	A
Pulsed Current <sup>3</sup>	I <sub>SM</sub>				44	
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = I <sub>S</sub> , V <sub>GS</sub> = 0V			1.3	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = I <sub>S</sub> =8A, di <sub>F</sub> /dt = 100A / mS		7.2		nS
Reverse Recovery Charge	Q <sub>rr</sub>			0.26		nC

<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Pulse width limited by maximum junction temperature.

EMC will review datasheet by quarter, and update new version.



▪ TYPICAL CHARACTERISTICS

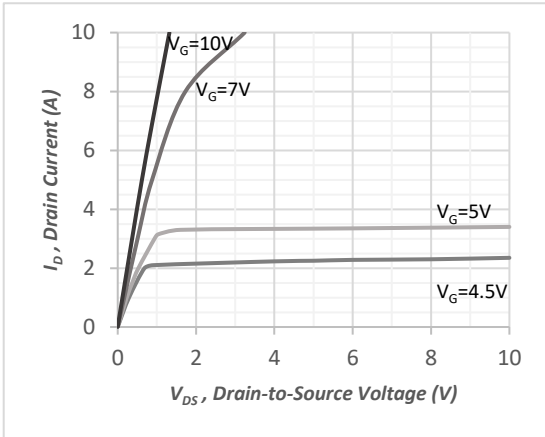


Fig.1 Typical Output Characteristics

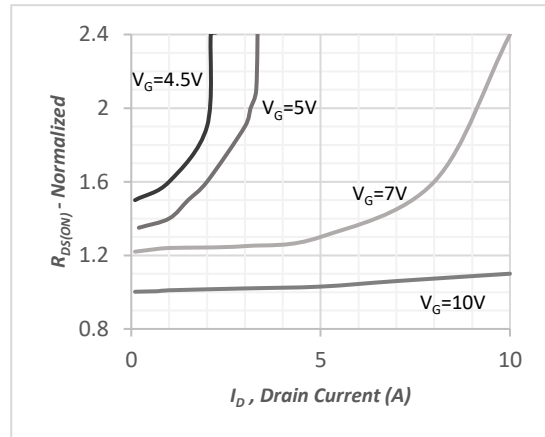


Fig.2 On-Resistance vs. Drain Current

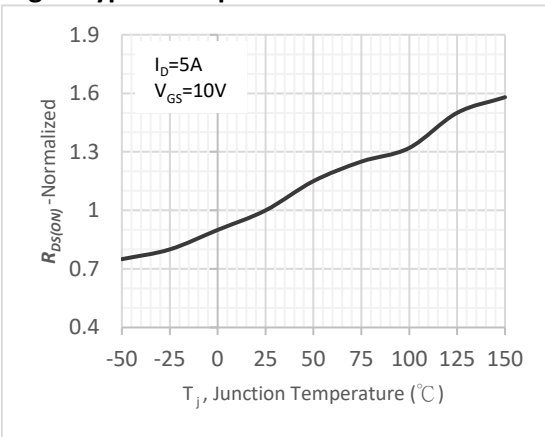


Fig.3 Normalized On-Resistance v.s. Junction Temperature

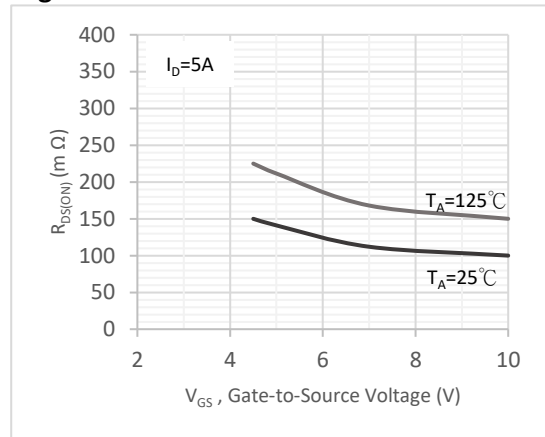


Fig.4 On-Resistance v.s. Gate Voltage

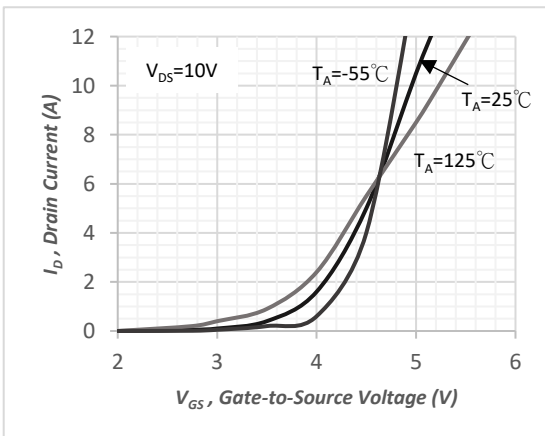


Fig.5 Forward Characteristic of Reverse Diode

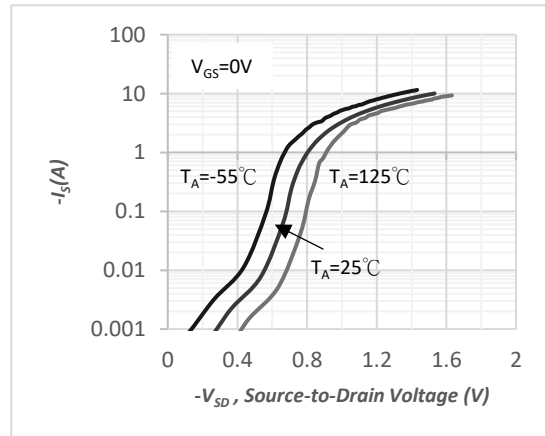


Fig.6 Transfer Characteristics

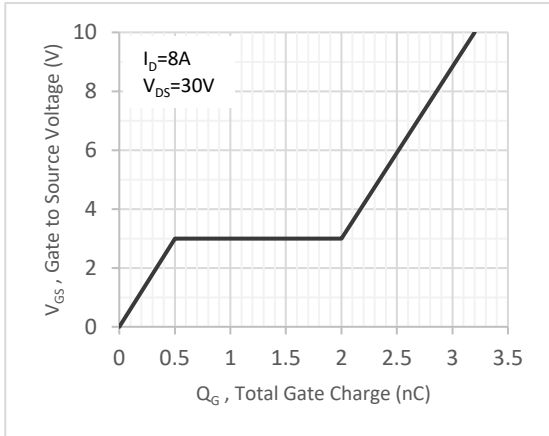


Fig.7 Gate Charge Characteristics

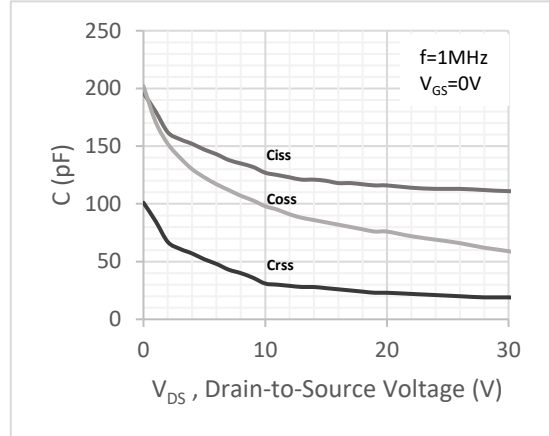


Fig.8 Typical Capacitance Characteristics

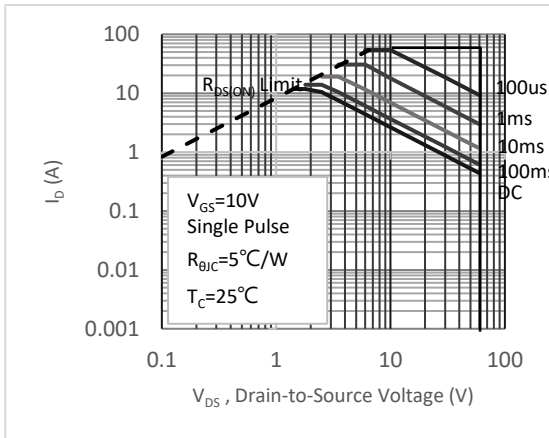


Fig.9. Maximum Safe Operating Area

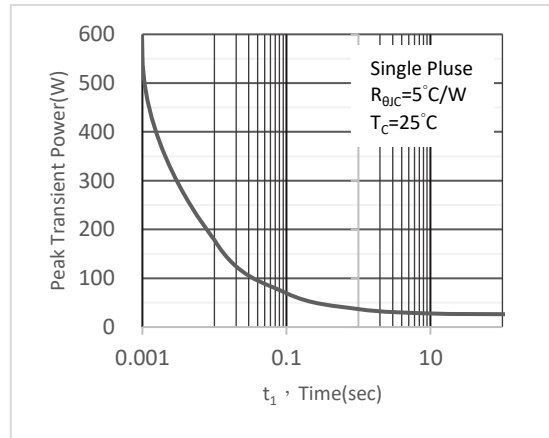


Fig.10. Single Pulse Maximum Power Dissipation

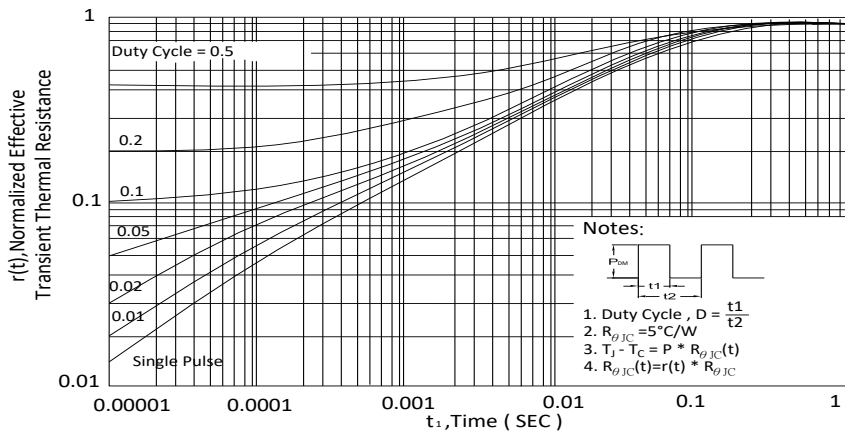


Fig.11. Effective Transient Thermal Impedance



Ordering & Marking Information:

Device Name: EMBA2A06HS for EDFN 5x6



BA2A06S: Device Name

ABCDEFG: Date Code

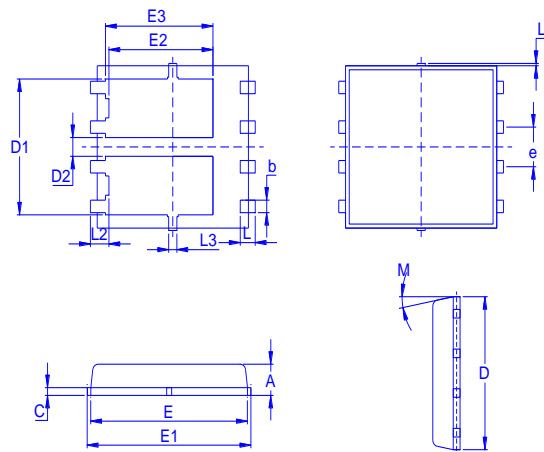
A: Assembly House

B: Year(A:2008 B:2009 C:2010...)

C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

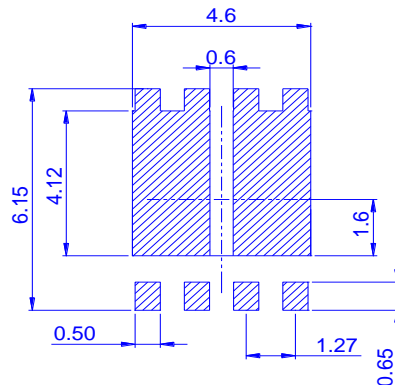
DEFG: Serial No.

Outline Drawing

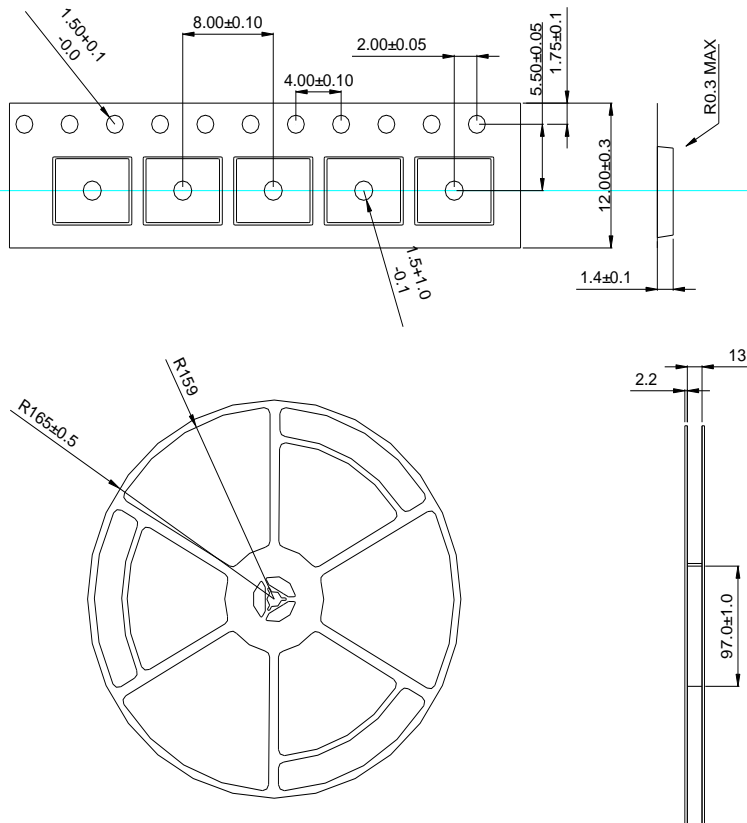


Dimension	A	b	c	D	D1	D2	E	E1	E2	e	L	L1	L2	M
Min	0.85	0.3	0.15			0.5					0.45	0		0°
Typ.	0.95	0.4	0.2	5.2	4.35	0.6	5.55	6.05	3.82	1.27	0.55		0.68	
Max	1	0.5	0.25			0.75					0.65	0.15		10°

Footprint



◆ **Tape&Reel Information:2500pcs/Reel(Dimension in millimeter)**



產品別	EDFN5X6
Reel尺寸	13"
編帶方式	<p>FEED DIRECTION</p>
前空格	25
後空格	50
裝箱數	
滿捲數量	2.5K
捲/內盒比	01:01
內盒滿箱數	2.5K
內/外箱比	10:01
外箱滿箱數	25K